Preferred Device

POWERTAP™ II SWITCHMODE™ Power Rectifier

This state-of-the-art SWITCHMODE Power Rectifier uses the Schottky Barrier principle with a platinum barrier metal.

Features

- Dual Diode Construction; May Be Paralleled for Higher Current Output
- Guard-Ring for Stress Protection
- Low Forward Voltage Drop
- 150°C Operating Junction Temperature
- · Recyclable Epoxy
- Improved Mechanical Ratings
- Pb-Free Package is Available*

Mechanical Characteristics

- Case: Epoxy, Molded with metal heatsink base
- Weight: 80 grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant
- Top Terminal Torque: 25-40 lb-in Max
- Base Plate Torques: See procedure Given in the Package Outline Section

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
Average Rectified Forward Current (At Rated V_R , $T_C = 100^{\circ}C$) Per Leg Per Device	I _{F(AV)}	200 400	А
Peak Repetitive Forward Current, (At Rated V _R , Square Wave, 20 kHz, T _C = 100°C)	I _{FRM}	200	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	IFSM	1500	A
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	I _{RRM}	2.0	Α
Storage Temperature Range	T _{stg}	-55 to +150	°C
Operating Junction Temperature	TJ	-55 to +150	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/μs

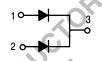
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

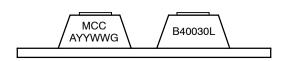
http://onsemi.com

LOW V_F SCHOTTKY BARRIER RECTIFIER 400 AMPERES, 30 VOLTS





MARKING DIAGRAM



B40030L = Specific Device Code
MCC = Mold Compound Code
A = Assembly Location

YY = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
MBRP40030CTL	POWERTAP II	25 Units/Tray
MBRP40030CTLG	POWERTAP II (Pb-Free)	25 Units/Tray

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

THERMAL CHARACTERISTICS

(Rated dc Voltage, T_C = +25°C)

(Rated dc Voltage, $T_C = +100^{\circ}C$)

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Note 1)	$R_{ heta JC}$	0.4	°C/W
ELECTRICAL CHARACTERISTICS			
Maximum Instantaneous Forward Voltage (Note 2)	V _F		V
$(i_F = 200 \text{ Amps}, T_C = +25^{\circ}\text{C})$		0.5	
(i _F = 200 Amps, T _C = +100°C)		0.41	
Maximum Instantaneous Reverse Current (Note 2)	I _R		mA

[.] Rating applies when surface mounted on the minimum pad size recommended.

^{2.} Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2%.

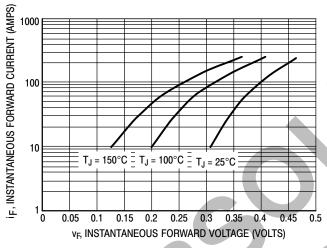
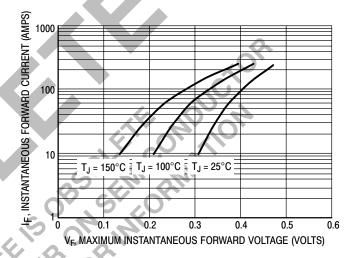


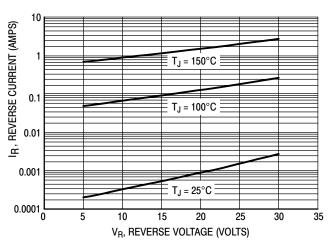
Figure 1. Typical Instantaneous Forward Voltage



20

1000

Figure 2. Maximum Instantaneous Forward Voltage



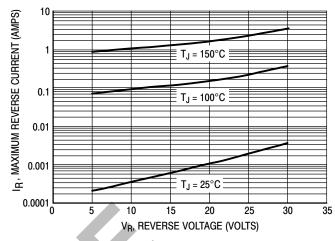
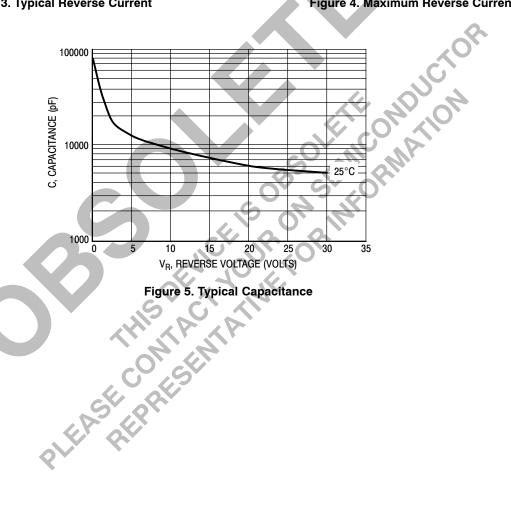


Figure 3. Typical Reverse Current

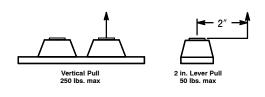
Figure 4. Maximum Reverse Current



MAXIMUM MECHANICAL RATINGS

Terminal Penetration:	0.235 max
Terminal Torque:	25-40 in-lb max
Mounting Torque – Outside Holes:	30-40 in-lb max
Mounting Torque – Center Hole:	8–10 in-lb max
Seating Plane Flatness	1 mil per in. (between mounting holes)

POWERTAP MECHANICAL DATA APPLIES OVER OPERATING TEMPERATURE



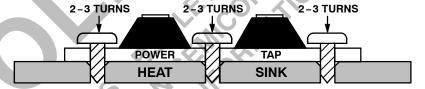
Note: While the POWERTAP is capable of sustaining these vertical and levered tensions, the intimate contact between POWERTAP and heat sink may be lost. This could lead to thermal runaway. The use of very flexible leads is recommended for the anode connections. Use of thermal grease is highly recommended.

MOUNTING PROCEDURE

The POWERTAP package requires special mounting considerations because of the long longitudinal axis of the copper heat sink. It is important to follow the proper tightening sequence to avoid warping the heat sink, which can reduce thermal contact between the POWERTAP and heat sink.

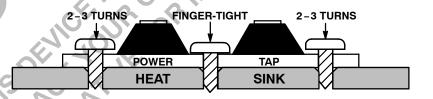
STEP 1:

Locate the POWERTAP on the heat sink and start mounting bolts into the threads by hand (2 or 3 turns).



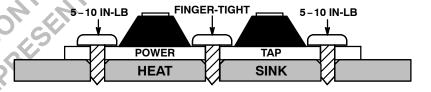
STEP 2:

Finger tighten the center bolt. The bolt may catch on the threads of the heat sink so it is important to make sure the face of the bolt or washer is in contact with the surface of the POWERTAP.



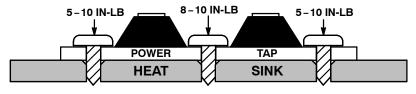
STEP 3:

Tighten each of the end bolts between 5 to 10 in-lb.



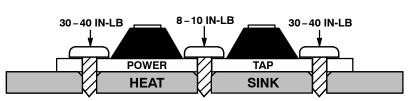
STEP 4:

Tighten the center bolt between 8 to 10 in-lb.



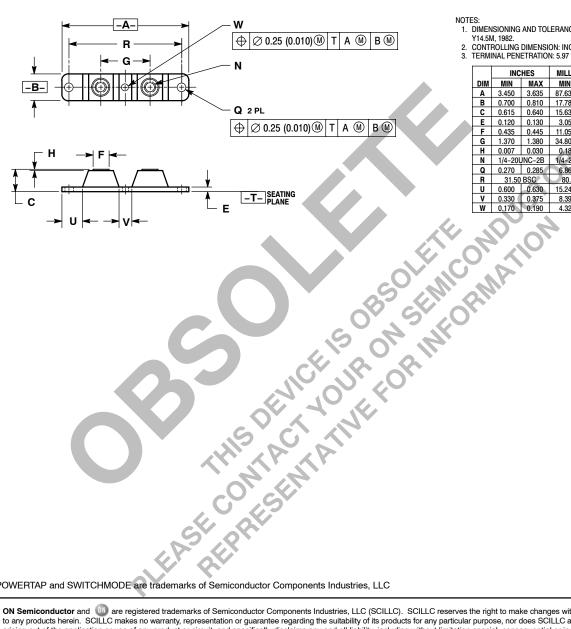
STEP 5:

Finally, tighten the end bolts between 30 to 40 in-lb.



PACKAGE DIMENSIONS

CASE 357C-03 POWERTAP PLASTIC PACKAGE ISSUE E



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- TERMINAL PENETRATION: 5.97 (0.235) MAXIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	3.450	3.635	87.63	92.33
В	0.700	0.810	17.78	20.57
С	0.615	0.640	15.63	16.26
Е	0.120	0.130	3.05	3.30
F	0.435	0.445	11.05	11.30
G	1.370	1.380	34.80	35.05
Н	0.007	0.030	0.18	0.76
N	1/4-20	JNC-2B	1/4-201	JNC-2B
Q	0.270	0.285	6.86	7.23
R	31.50 BSC		80.01 BSC	
U	0.600	0.630	15.24	16.00
٧	0.330	0.375	8.39	9.52
W	0.170	0.190	4.32	4.82

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